

2010 CPMT CONFERENCES AND WORKSHOPS

2010 11th Thermal, Mechanical and Multiphysics Simulation and Experiments in Micro-Electronics and Micro-Systems Conference (EuroSimE 2010)

April 26-28 2010 Bordeaux, France
<http://www.eurosime.org/>
Contact: eurosime@astefo.com

2010 Design, Test, Integration and Packaging of MEMS/MOEMS (DTIP 2010)

May 5-7 .2010 Seville, Spain
<http://cmp.imag.fr/conferences/dtip/dtip2010/>
Contact: Chantal Bénis-Morel, chantal.benis@imag.fr

2010 14th IEEE Workshop on Signal Propagation on Interconnects (SPI 2010)

May 9-12, 2010 Hildesheim, Germany
<http://www.spi.uni-hannover.de/>
Contact: Uwe Arz, Physikalisch-Technische Bundesanstalt, uwe.arz@ptb.de

2010 60th Electronic Components and Technology Conference (ECTC 2010)

June 1 - 4, 2010 Las Vegas, NV, USA
<http://www.ectc.net>
Contact: Jean Trehwella, jeanmh@us.ibm.com

2010 20th IEEE Semiconductor Wafer Test Workshop (SWTW 2010)

June 6-10, 2010, San Diego, CA USA
<http://www.swtest.org/index.html>
Contact: Maddie Harwood, maddie@cemamerica.com

2010 IEEE/SEMI Advanced Semiconductor Manufacturing Conference (ASMC 2010)

July 11-13, 2010 San Francisco CA, USA
<http://www.semi.org/asmc2010>
Contact: Margaret Kindling, SEMI, mkindling@semi.org

2010 6th Annual Organic Microelectronics and Optoelectronics Workshop

July 6-9, 2010, San Francisco CA, USA
<http://acswebcontent.acs.org/organicmicroelectronic/index.html>
Contact: organic_microelectronics@acs.org

2010 International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP 2010)

August 16-19, 2010 Xi'an, China
<http://www.icept.org>
Contact: icept2010@xidian.edu.cn

2010 Electronics System-Integration Technology Conference (ESTC 2010)

September 13-16, 2010 Berlin, Germany
<http://www.estc-2010.de/>
Contact: estc2010@izm.fraunhofer.de

2010 55th IEEE Holm Conference on Electrical Contacts (HOLM 2010)

October 4-7, 2010 Charleston, SC, USA
<http://www.ewh.ieee.org/soc/cpmt/tc1>
Contact: Alicia Zupeck a.zupeck@ieee.org

2010 16th Int'l Workshop on Thermal Investigations of ICs and Systems (THERMINIC 2010)

October 6-8, 2010 Leuven, Belgium
<http://cmp.imag.fr/conferences/therminic/therminic2010>
Contact: Chantal Bénis-Morel, chantal.benis@imag.fr

2010 IEEE/CPMT Workshop on Accelerated Stress Test and Reliability (ASTR 2010)

October 6-8, 2010 Denver, CO, USA
<http://www.ewh.ieee.org/soc/cpmt/tc7/ast2010/>
Contact: Michael P. O'Keefe, michael.okeefe@nrel.gov

2010 5th Int'l Microsystems, Packaging, Assembly and Circuits Technology (IMPACT 2010)

October 20-22, 2010 Taipei, Taiwan
<http://www.impact.org.tw/2010/General/>
Contact: service@impact.org.tw

2010 19th IEEE Electrical Performance of Electronic Packaging (EPEP 2010)

October 25-27, 2010 Austin, TX, USA
<http://www.epep.org>
Contact: Kelly Sutton epd@engr.arizona.edu

2010 12th Electronics Packaging Technology Conference (EPTC 2010)

December 8-10, 2010 Singapore
<http://www.eptc-ieee.net/>



Highlighting Solutions That Improve the Semiconductor Manufacturing Process

For over 20 years, the Advanced Semiconductor Manufacturing Conference (ASMC) has filled a critical need in our industry by providing a venue for industry professionals to network, learn and share knowledge on new and best-method semiconductor manufacturing practices and concepts.

The conference synergy leads to understandings and relationships which can benefit participating companies in a variety of ways, including accelerating innovation, promoting successes, and getting a more thorough understanding of standards and benchmarks.

In 2010, ASMC moves to San Francisco, opening up greater opportunities. For industry professionals to meet and discuss critical issues in semiconductor manufacturing. By co-locating with SEMICON West, ASMC will continue a long tradition of unveiling breakthroughs in semiconductor manufacturing—from fab productivity to advanced process controls and device yield.

July 11-13, 2010 – San Francisco Marriott Marquis

Keynotes

ASMC is pleased to announce our keynote line-up for 2010:

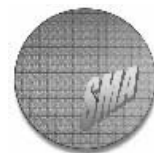
Matt Nowak, Director of Engineering in the VLSI Technology Group, Qualcomm
Bill McClean, president, IC Insights
Kelin Kuhn, Intel Fellow; director, Advanced Device Technology, Intel Corporation

Who Should Attend

Technical managers, engineers, plant managers and other semiconductor professionals involved:

- Production Control
- Process Development
- Fab Operations
- Device Characterization
- Cycle Time Improvement
- Cost Reduction
- Fab Productivity
- Preventative Maintenance
- Line Supervision
- Product Management
- Yield Enhancement

Co-sponsors





CALL FOR PAPERS

The International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP 2010) is to be held in Xi'an, China, from August 16 to 19, 2010. Until 2009, ICEPT-HDP, which is organized by Electronic Manufacturing and Packaging Technology Society (EMPT) of Chinese Institute of Electronics, has been successfully held for ten times by some leading universities such as Tsinghua University, Fudan University, Harbin Institute of Technology, Huazhong University of Science & Technology and Shanghai Jiaotong University. This conference has provided a great technical platform for international and domestic experts, scholars, and researchers from academia and industries to exchange their ideas on the development of electronic packaging. As one of the most famous international conferences on electronic packaging technology, it was greatly supported by IEEE-CPMT, IMAPS, ASME and iNEMI, and highly appreciated by China Institute of Electronics and China Association of Science.

ICEPT-HDP 2010, co-organized by Xidian University, is a 4-day event. The conference will feature short courses, conference keynotes, special forums, technical sessions and posters to cover the technological developments in all the areas of electronic packaging. You are welcomed to submit an abstract and attend the conference. More information can be found at www.icept.org.

CONFERENCE THEMES

- **Advanced Packaging & System Integration:** BGA, CSP, flip chip; WLP, SoP, SiP; 3D packaging, PoP, TSV; micro- & nano-system packaging; and other advanced packaging and system integration technologies.
- **Packaging Materials & Processes:** New developments in bonding wires, solders, underfills, encapsulations, adhesives, thin films, dielectrics, substrate materials, conductive adhesives and thermal conductive materials; green electronics materials, nanomaterials and other novel materials for packaging performance enhancement and cost reduction; and various packaging/assembly processes.
- **Packaging Design and Modeling:** Various new packaging/assembly designs; methods/technologies/software for modeling, simulation and validation of electrical, thermal, optical and mechanical performance of various electronics packages; chip-packaging-PCB co-design; and multi-function & scale modeling, simulation, validation methods/software.
- **High Density Substrate & SMT:** Substrate with embedded passives and active components; micro-via, micro-joint, HDI substrate, PCB, high performance multi-layer substrate; stencil print, reflow; and other novel assembly technologies that improve substrate density and performance.
- **Packaging Equipment & Advanced Manufacturing Technologies:** New packaging/assembly equipment; packaging equipment/measurement techniques for emerging technologies; photolithography, laser processing; novel packaging/assembly technologies for manufacturability and yield improvement, cost reduction and service performance improvement; and methods/software for modeling and monitoring of process effectiveness & cost analysis.
- **Quality & Reliability:** Quality monitoring and evaluation for packaging/assembly; advanced methods/technologies/tools for rapid reliability data collection/analysis, reliability modeling & life prediction; reliability issues in advanced electronics packages; failure analysis, non-destructive diagnose, and yield analysis.
- **Emerging Technologies:** Packaging technologies for Sensors, actuators, MEMS, NEMS & MOEMS; optoelectronics & LED packaging; LCD, passive & RF devices, power & HV devices; nano-devices based on nano-wires, nano-tubes and polymers, etc.

SUBMISSION OF ABSTRACT/PAPER

Abstracts are solicited to describe original and unpublished work. The abstract should be approx. 500 words and contains a clear statement of the background, methodology, results, conclusions, and important references of the work. All abstracts must be in English and should be submitted using the format provided in the attached word file to icept2010@xidian.edu.cn.

The abstracts must be received by **April 6, 2010**. Authors must include their affiliations, mailing addresses, telephone and fax numbers, and email addresses. Authors will be notified of paper acceptance by **April 30, 2010**. The final manuscripts for publication in the conference proceedings are due by **July 16, 2010**. Selected papers will be recommended for publication in IEEE/CPMT journals.

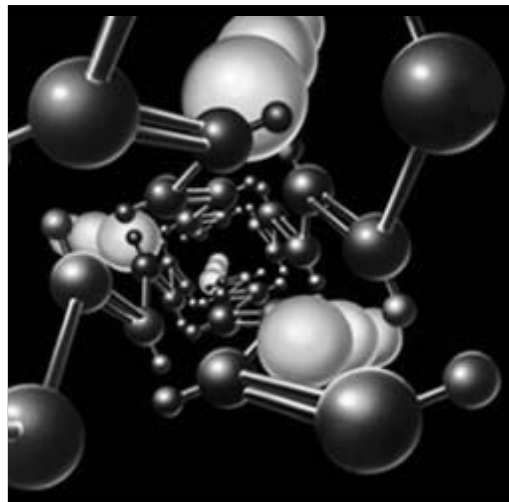
CALL FOR EXHIBITION/SPONSORSHIP

A tabletop exhibition featuring suppliers of materials, equipment, components and software, manufacturers, and service providers of the electronics packaging and related industries will be held during the conference. Potential exhibitors and sponsors may email icept2010@xidian.edu.cn; for details.

IMPORTANT DATES

- **April 6, 2010** – Deadline for Submission of Abstract
- **April 30, 2010** – Notification of Acceptance
- **July 16, 2010** – Deadline for Submission of Manuscript

CALL FOR PAPERS



Organic Microelectronics & Optoelectronics Workshop VI

www.organicmicroelectronics.org

July 6 – 9, 2010

Marriott San Francisco Marquis
San Francisco, CA , USA

The workshop will bring together a broad spectrum of chemists, materials scientists, physicists, and engineers from both industry and academia in a stimulating forum to share information and ideas in the emerging field of Organic Microelectronics. The goal is to build an interdisciplinary community working on applications such as RFIDs, displays, sensors and photovoltaics while addressing some of the common scientific and manufacturing challenges to help these technologies advance in a more rapid, effective, and economical manner.

The technical program will focus on the areas of synthesis, theory, novel processing/ patterning/fabrication and device physics through a series of presentations by renowned invited speakers and poster sessions.

INVITED SPEAKERS

Magnus Berggren, Linköping University (Sweden)
Paul Blom, Holst Centre (Netherlands)
Jochen Brill, BASF (Germany)
Dago DeLeeuw, Philips/Univ. Groningen (Netherlands)
Antonio Facchetti, Polyera (USA)
Gitti Frey, Technion (Israel)
David Ginger, U. Washington (USA)
David Gundlach, NIST (USA)

CONTRIBUTED PAPERS

The Organic Microelectronics Workshop will feature additional 20 minute contributed talks along with a poster session in addition to the invited speakers. This will give you the opportunity to share your recent findings, peruse others' work and exchange opinions with your fellow participants. Join the lively and informal discussions, discover new avenues for research, and get acquainted with other scientists in your industry.

If you are interested in presenting an oral or poster paper at the workshop, please see submission instructions at: <http://acswebcontent.acs.org/organicmicroelectronic/posters.html>. The abstract should not exceed 250 words, and it should be e-mailed no later than April 15, 2010 to organic_microelectronics@acs.org. Earlier submissions are appreciated. Please specify whether you are interested in making a poster or oral presentation.

You will receive an e-mail from the organizers acknowledging receipt of your abstract. We will let you know if your abstract has been accepted no later than May 1.

Deadline for all submissions is April 15, 2010.

2010 Chairs

- **Edwin Chandross**
(General Chair)

Affiliation

Materials Chemistry LLC

- **Ana Claudia Arias**

Palo Alto Research Center (PARC)

- **Michael Chabinyc**

University of California

- **Tom Jackson**

The Pennsylvania State University

Paul Heremans, IMEC (Belgium)
Russell Holmes, U. Minnesota (USA)
Oana Jurchescu, Wake Forest Univ. (USA)
Alberto Salleo, Stanford U. (USA)
Charles Sodini, MIT (USA)
Takao Someya, U. Tokyo (Japan)
Shawn Williams, Plextronics (USA)





Thermal investigations of ICs and Systems

Barcelona, Spain

6-8 October 2010

Sponsored by:



IEEE Components, Packaging and Manufacturing Technology Society

Preliminary Call for Papers

THERMINIC Workshops are a series of events to discuss the essential thermal questions of microelectronic microstructures and electronic parts in general. These questions are becoming more and more crucial with the increasing element density of circuits packaged together and with the move to nanotechnology. These trends are calling for thermal simulation, monitoring and cooling. Thermal management is expected to become an increasingly dominating factor of a system's cost. The growing power dissipated in a package, the mobile parts of microsystems raise new thermal problems to be solved in the near future necessitating the regular discussion of the experts in these fields. Finally, there is an increasing need for accurate assessment of the boundary conditions used in the analysis of electronic parts, which requires a concurrent solution of the thermal behaviour of the whole system.

This year THERMINIC will address in addition to the "traditional" thermal management problems, also stress and thermal-stress-related-reliability issues, both in micro- and optoelectronics fields. These issues, including various nanotechnology applications, are of significant importance and of high interest to the engineering community engaged in the field of thermal phenomena in "high-tech" systems.

The Workshop is sponsored by the IEEE Components, Packaging, and Manufacturing Technology Society and by CMP.

AREAS OF INTEREST include, but are not limited to, the following topics:

- Thermal and Temperature Sensors
- Thermal Simulation
- Electro-thermal Simulation
- Thermal Modelling & Investigation of Packages
- Reliability Issues
- High Temperature Electronics
- Heat Transfer Education
- Flow Visualisation Techniques
- Turbulence Modelling in Complex Geometries
- Defect and failure modelling
- Reliability evolution and prediction
- Multiphysics simulation
- Nanoengineering issues
- Education
- Measurement of Thermal Properties
- Acquisition and analysis of Thermal data
- Temperature Mapping
- Novel and Advanced Cooling Techniques
- Thermal Performance of Interconnects
- Heat Transfer Enhancement
- Validation of Thermal Software
- Coupled (Thermo-mechanical, Thermo-optical, etc.) Effects
- Thermal Stress: Theory and Experiment
- Thermal Stress Failures: Prediction and Prevention
- Nanotechnology Applications
- Noise control.

TECHNICAL PROGRAMME will include oral talks, poster presentations, a panel discussion, and invited talks given by prominent speakers.

AUTHORS ARE INVITED to submit electronic papers describing recent work. Panel proposals are also invited. Papers may be extended summaries or full papers although preference will be given to full paper submissions. In either case, clearly describe the nature of the work, explain its significance, highlight novel features, and describe its current status. Submission will be electronically only. Only papers of PDF (.pdf) format can be submitted. Detailed information about the submission process will be made available on the THERMINIC Web site:

<http://cmp.imag.fr/conferences/therminic/therminic2010>

In case you experience any problems with the submission procedure, please contact the General Chair, Bernard Courtois, CMP, Grenoble, France. E-mail: THERMINIC@imag.fr

Accepted contributions will be included in Workshop Proceedings.

Submission deadline:	30 April 2010
Notification of acceptance:	15 June 2010
Submission of manuscripts for distribution at the Workshop:	08 September 2010

VENDORS AND BOOK EXHIBITIONS are invited to offer products in the scope of the Workshop to exhibit. Editors are invited to exhibit books.

SPECIAL ISSUES AND SPECIAL SECTIONS of leading periodicals have been organised regarding the previous Workshops (Journal of Sensors and Actuators, Microelectronics Journal, IEEE Transactions on VLSI Systems, IEEE Transactions on Components and Packaging Technologies, Journal of Electronic Packaging). It is again expected to have special issues and special sections of leading periodicals as follow up of the Workshop 2010.

VENUE:

The workshop is hosted at the Novotel Barcelona City. Barcelona is the cultural, administrative, economic and historic capital of Catalonia province of Spain. Due to its huge importance in finance, publication, arts, entertainment and Medias, Barcelona is considered as a world culture town. The city is served by air, train, bus or boat and its flavours, sounds and smells, emphasized by awesome landscapes, will make your THERMINIC attendance unforgettable. More information: <http://www.bcn.es/turisme/english/turisme/welcome.htm> or <http://www.barcelonaturisme.com>

Check the web site for more information:
<http://cmp.imag.fr/conferences/therminic/therminic2010>

THERMINIC Workshop

General Chair

B. Courtois, CMP Grenoble, France

Vice General Chair

M. Rencz, BUTE, Budapest, Hungary

Programme Chairs

J. Altet, UPC, Barcelona, Spain

A. Rubio, UPC, Barcelona, Spain

Programme Committee

To include

A. Daniel, Intel, USA

K. Chakrabarty, Duke, USA

T. Persoons, KU Leuven, Belgium

O. Chapuis, CIN2-

CSIC, Barcelona, Spain

Y. Gianchandani, U. of Michigan, USA

S. Volz, Ecole Centrale Paris, France

V. Evely, The Petroleum Inst., UAE

M. Shin, Myong Ji U., Korea

I. Barsony, KFKI-ATKI, Hungary

H.g Chiueh, National Chiao Tung U., Taiwan

G. De Mey, Ghent U., Belgium

R. Egawa, Tohoku U., Japan

S. Garimella, Purdue U., West Lafayette, USA

B. Michel, IBM Zurich, Rueschlikon, Switzerland

P. Rodgers, The Petroleum Inst., UAE

E. Suhir, U.C Santa Cruz, USA

F.n Udrea, U. of Cambridge, UK

B. Vandewelde, IMEC, Belgium

S. Sapatnekar, U. of Minnesota, USA

X. Jorda, Centro Nacional de Microelectrónica, Spain

V. Tsoi, Huawei Techno, Kista, Sweden

Y.k Christian Gerstenmaier, Siemens, Germany

W. Faris, IILUM, Malaysia

A. Tay, NUS, Singapore

T. Baba, Nat. Metrology Institute Tsukuba, Japan

N. Taketoshi, AUST, Ivbaraki, Japan

P. Raad, South. Methodist U., USA

S. Bouwstra, MEMS Technical Consultancy, Amsterdam, The Netherlands

Y. Scudeller, E.Polytech. U. Nantes, France

A. Glezer, The Georgia Inst. of Techno., USA

T. Zahner, OSRAM, Germany

A. Aranyosi, Electr. Cooling Solutions Inc., Santa Clara, USA

G. Wachutka, TU Munchen, Germany

H. Pape, Infineon Techn., Germany

A. Shakouri, U. of California, USA

V. Natarajan, Intel India, Bangalore, India

M-N. Sabry, U. Française d'Egypte, Egypt

J. Janssen, NXP Semiconductors, Nijmegen, The Netherlands

W. Luiten, Philips Applied Technologies, Eindhoven, The Netherlands

Abstract Deadline : May 31st, 2010

FIRST ANNOUNCEMENT AND CALL FOR PAPERS

About IEMT

The 34th Electronics Manufacturing Technology Conference (IEMT 2010) will be held in Melaka, Malaysia. It is an international event organized by the IEEE CPMT Malaysia Chapter with co-sponsorship from CPMT society of IEEE, Santa Clara Valley Chapter. IEMT 2010 will feature short courses, 4 parallel technical sessions, and table top exhibition. It aims to provide good coverage of technological developments in all areas of electronics packaging, from design to manufacturing and operation. IEMT 2010 is a major forum, providing opportunities to network and meet leading experts, in addition to exchange of up to date knowledge in the field. Since 1990's, IEMT has gained a reputation as a premier electronics materials and manufacturing technology conference and is well attended by experts in all aspects related to packaging technology from all over the world.

Conference Topics

The topics of interests are specific to manufacturing and test technology, micro systems/MEMS, their packaging, electronics materials, board level assembly and reliability issues. Extended abstracts are being sought from, but not limited to, the following areas:

- Manufacturing Technologies
- Surface Mount Technology
- Advanced/3D Packaging
- Interconnection Technologies
- Emerging Packaging Technologies
- IC Testing Technology
- Materials & Processes
- MEMS & Sensor Packaging
- Electrical Modeling & Signal Integrity
- Thermal Characterization & Cooling Solutions
- Mechanical Modeling & Structural Integrity
- Quality and Reliability
- Chip-Scale Packaging/Flip Chip
- LED Packaging
- Green Package

Important Dates:

Submission of Abstract	31st May 2010
Notification of Acceptance	30th Jun 2010
Submission of Manuscript	15th Aug 2010

Conference Information and Contacts

IEMT2010 Secretariat
Infineon Technologies (Malaysia) Sdn. Bhd.
FTZ , Batu Berendam, 75350 Melaka, Malaysia
Tel : +6-06-230 3480
Fax : +6-06-231 4233
Email : Tracy.Ow@infineon.com
Conference website: <http://ewh.ieee.org/r10/malaysia/cpmt/iemt.htm>
Melaka Tourism : <http://www.melaka.net/>

Extended Abstract and Paper Submission

Extended abstracts are invited to describe original and unpublished works. They should be about 500 words stating clearly the purpose, methodology, results, and conclusions of the work. Key references to prior publications and how the work enhances the existing knowledge should be included in the extended abstract. Authors are requested to designate appropriate areas for the purpose of abstract review. All submissions must be in English and should be made via electronic mail to conference secretariat. Author may send their abstract either in MS Word or Adobe Acrobat® PDF format with only one single file for each submission. The abstracts must be sent to secretariat via email by 31st May, 2010. Authors are requested to include their affiliation, mailing address, telephone and fax numbers, and e-mail address. Authors will be notified of paper acceptance and instruction for preparing final papers by 30th June, 2010. The final manuscript for publication in the conference proceedings is due by 15th August 2010.

Call For Exhibition

A tabletop exhibition from suppliers of materials, equipment, components, software, and service providers of electronics industries will also be held at the venue of the conference. Potential exhibitors and sponsors may email our secretariat for more details.

Conference Best Paper Awards

The conference will present the “**Best paper Award**” to papers in various categories. The overall best paper will receive **RM3000** in cash. Second runner-up will receive **RM2000**. Best poster paper will receive **RM1000**. The conference will also present a cash award of **RM1000** to student best paper.

Free Tour Around The City of Malacca/Cultural Show

We will take the participants for a tour around the historical city of Melaka. They will also be entertained by the local cultural groups while having dinner on various local delicacies. We will make further announcement when more information is available.

Keynotes / Short Courses

The conference will have attractive keynotes and short courses on the latest manufacturing technology and advanced packaging conducted by experts in the field. We will announce further details when more information becomes available.



Joint 25th ICEC & 56th IEEE Holm Conference on Electrical Contacts
4-7 October, 2010, Charleston, South Carolina USA
Intensive Course on Electrical Contacts

**Joint Meeting of 25th International Conference & 56th IEEE Holm Conference
on Electrical Contacts**

Purpose

To provide a forum for the presentation and discussion of the latest developments in the field of electric contacts and the application of recent advances in materials and processes in electric, electronic and telecommunication equipment. The International Conference is a bi-annual event that is hosted by countries in Europe, Asia and North America in rotation. 2010 will be an exciting joint conference with the North America IEEE Holm Conference event. Typically, up to 60+ technical papers will be presented over four days in the conference with extra opportunities for international networking.

For Whom

Practicing designers, engineers, physicists and research scientists - those new to the field and those experienced. The 2010 Joint Conference will include excellent papers authored by some of the outstanding technical people in this field. The international contributors come from universities and industries in USA, Austria, Canada, Japan, China, France, Switzerland, Russia, Germany, United Kingdom and other countries. These papers will provide the attendees with up-to-date information on a wide range of subjects that makes this conference so attractive to the practicing engineer. Additionally, the joint conference will make it possible for any attendee to discuss with other international authors, on work presented by the author at the conference or any subject related to the author's field of expertise.

Background

The Holm Conference began in 1953 as a forum for the discussion of electrical contact phenomena and related fields. In 1968, the conference was named the Holm Conference in honor of Dr. Ragnar Holm. Dr. Holm, whose contributions to the field of electrical contacts spanned 50 years and form the foundation of the electrical contacts field, was the inspiration and guide of the Conference from its inception until his death in 1970. In 1985, IEEE society started sponsoring the conference as a recognition of its importance in the field of electrical engineering. In addition to the Annual Conference, the Conference Organization regularly conducts an intensive one-week course on contacts and participates in the biannual International Conference on Electrical Contacts.

The International Conference on Electrical Contact started in 1961 with an International Advisory Group from the industrial nations. This was in recognition of the international scientific activities in the field of electrical contacts. The last 3 International Conference were held in Seattle USA (2004), Sendai Japan (2006) and St. Malo France (2008)

Four days of presentations normally includes over 60 Technical Papers, the Ragnar Holm Scientific Achievement Award, the Dr. Morton Antler Lecture and hot topic panel workshops. They highlight the most recent electrical contact work all over the world.

Contacts Properties and Performance, Connector Contacts, Sliding Contacts, Aluminum Contacts, Arcing Contacts, Silver Metal Oxide Contacts, MEM Systems, Automotive Switches and Relays, Superconductor Contacts, and Real world Design and Applications Problems are familiar themes in the presentation. Recent activities on Arc Fault Detection, AFCL, Smart Grid, ROHS and renewable power generation are adding new themes to the technical program.

ITherm 2010

Bally's, Las Vegas, Nevada, USA

June 2-5, 2010

www.ithermconference.org/home.html

Co-located with ECTC

ITherm 2010 is an international conference for scientific and engineering exploration of thermal, thermomechanical and emerging technology issues associated with electronic devices, packages and systems. ITherm 2010 will be held along with the 60th Electronic Components and Technology Conference (ECTC 2010 - <http://www.ectc.net>), a premier electronic packaging conference. In addition to paper and poster presentations and vendor exhibits, ITherm 2010 will include panel discussions, keynote lectures by prominent speakers, and professional short courses.

ITherm 2010 will feature original Oral and Poster presentations addressing latest developments in research and technology.

Tutorials (first day of Conference) are included in the registration fee. No additional fee is required. Registrants will receive a copy of the course notes for all courses and may attend as many as can fit in to the schedule. Topics include:

- Energy Efficient Thermal Management of Data Centers
- Employing Innovative Cooling Technologies in Present and Future Electronic Products
- High Resolution Thermal Metrology for Electronic Systems
- An Introduction to the Analysis of Delamination in IC Packages Using Fracture Mechanics
- Carbon Nanotube and Graphene Nanoribbon Interconnects
- Mechanics of Interfaces in Microelectronic Packaging
- Design of Experiments for Thermal Engineering
- Thermoelectric Modules: Principles and Research
- Thermal Engineering of Phase Change Random Access Memory (PCRAM) Devices
- On-Chip Thermal Management and Hot Spot Remediation
- Advanced Cooling Technologies for Next-Generation Microelectronics Systems
- Measurement Techniques in the Thermal Management of Electronics

Prof. Yogendra Joshi
General Chair, ITherm 2010
Email: yogendra.joshi@me.gatech.edu

Sandeep Tonapi
Program Chair, ITherm 2010
sandeep.tonapi@anveshak.com

**IEEE Components, Packaging and Manufacturing
Technology Society**

Marsha Tickman, Executive Director
445 Hoes Lane
Piscataway, NJ 08854 USA



1-4 June 2010, Las Vegas, Nevada, USA

www.ectc.net

The premier international packaging, components, and microelectronics systems technology conference, the Electronic Components and Technology Conference (ECTC) strives to offer attendees an outstanding array of packaging technology information. This year's conference will have 39 technical sessions, 16 professional development courses, a panel discussion, a plenary session, a CPMT Seminar, and a technology corner for exhibitors. The 60th ECTC will be held at the Paris Las Vegas Hotel, Las Vegas, Nevada, USA from June 1 to June 4, 2010.

The technical program (oral and poster presentations) contains papers covering leading edge developments and technical innovations across the packaging spectrum. Topics include advanced packaging, modeling and simulation, optoelectronics, interconnections, materials and processing, applied reliability, assembly and manufacturing technology, components and RF, and emerging technologies. The Professional Development Courses offer state-of-the-art technology reviews and updates in a condensed half-day format. Topics cover a wide range of technologies.

The Panel Discussion, Plenary Session, and CPMT seminar in the evenings offer a format that allows for ample exchange and dialogue between the presenters and audience. They provide the conference participants the opportunity to gain the insight and perspective of technical and business leaders.

The Technology Corner complements the Technical Program by allowing companies to exhibit their products and services in an environment that enables discussion and interaction with the managers and engineers attending ECTC.

Last Day for Hotel Reservations: 3 May 2010

Last Day for Advanced Registration: 11 May 2010

A dark blue silhouette of the Berlin skyline is positioned at the top of the page. It includes the Fernsehturm (TV Tower) on the left, the Brandenburg Gate in the center, and various other buildings and structures. The skyline is set against a light blue background.

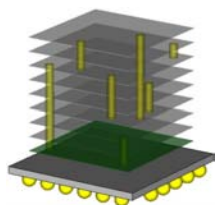
ESTC 2010

in Berlin, September 13–16, Maritim pro Arte

JOIN US IN BERLIN FOR THE 3RD ESTC CONFERENCE 2010!

Organized by IEEE's CPMT Society since 2006, the Electronic System Integration Technology Conference ESTC is the premier European event in assembly and interconnection technologies. The organizers are very pleased that 160 papers and 90 posters have been accepted for presentation at the conference. The concurrent exhibition will feature state-of-the-art technological services and equipment. Another highlight will be the half-day tutorials on various topics, ranging from non-destructive testing, polymers and nano-composites for electronic packaging to harsh environment packaging and 3D wafer level packaging.

Check out our website at www.estc-2010.de for more detailed information.



2010 IEEE Electrical Design of Advanced Packaging & Systems Symposium

December 7 – 9, 2010 in Singapore

The 2010 IEEE EDAPS Symposium

The IEEE Electrical Design of Advanced Packaging & Systems (EDAPS) has been the premier international symposium in Asia region since it was launched in 2002 in Singapore. Thereafter, it was held yearly in Korea (2003), Japan (2004), India (2005), Shanghai China (2006), Taiwan R. O. C (2007), Korea (2008) and Hong Kong China (2009). The EDAPS symposium consists of paper presentations, industry exhibitions, workshops and tutorials. The 2010 EDAPS will be held in Singapore again from December 7 to 9, 2010.

The purpose of EDAPS Symposium is to enhance the technical awareness and technology collaborations in the Asia region specifically in the electrical designs of chip, package and system levels from design concepts, technical challenges to the modeling and EDA tools. The papers of the symposium not only address the current technical issues but also bring out the challenges facing IC design, SiP/SoP packaging, EMI/EMC, and EDA tools and most importantly to address the challenge issues in 3D IC and packaging design. The symposium provides a major platform for researchers and practitioners from diverse fields to exchange knowledge and build up networks.

Important Deadlines and Dates

Proposal Submission for	
Special Session	July 15, 2010
Tutorial/Workshop	July 15, 2010
Proposal Acceptance Notice	July 30, 2010
Special Session Paper Submission	Sept. 30, 2010

Regular Paper (4-pages PDF) Submission	Sept. 30, 2010
Regular Paper Acceptance Notice	Oct. 15, 2010

<http://www.edaps2010.org>

Symposium Chair

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Call for Papers



Key Topics of the 2010 EDAPS

- Signal integrity topics including High-speed Digital Signal Integrity Modeling, Design, and Measurement;
- Power Distribution Network;
- System in Package (SiP) / System on Package (SoP) Design;
- High-performance Packaging for System on Chip (SoC);
- RF/Microwave Packaging for Wireless Communication and Mobile Phone;
- Interconnect Modeling, Simulation, and Measurement;
- Embedded Passives Modeling and Measurement;
- High-speed Channels Modeling and Measurement;
- 3D IC packaging including TSV, design, modeling and measurement;
- EMI/EMC and Electromagnetic Modeling and Measurement;
- EDA Techniques for Chip, Package, and Board Co-design and Simulation

Guidelines for Paper Submission

Authors are requested to submit a camera-ready 4-page paper, including title, author's affiliation, abstract, contents, figures and references. All submissions must be made through EDAPS website: www.edaps2010.org and must be in electronic format (PDF). A MS-Word template is available on the symposium website. Hardcopy submission will **NOT** be accepted.

Symposium Program

Tutorial / Workshop	Dec. 7, 2010
Plenary Speeches	Dec. 8, 2010
Oral Presentation	Dec 8 - 9, 2010
Poster Presentation	Dec 8 - 9, 2010
Exhibition	Dec 8 - 9, 2010
Banquet	Dec 8, 2010



EPTC 2010 Singapore

12th Electronics Packaging Technology Conference
8th - 10th December 2010

Mark Your Calendar for
EPTC 2010

CALL FOR PAPERS

Selected Publication in
IEEE Journals

ABOUT EPTC

The 12th Electronics Packaging Technology Conference (EPTC 2010) is an International event organized by the IEEE Reliability/CPMT/ED Singapore Chapter and sponsored by IEEE CPMT Society.

EPTC 2010 will feature technical sessions, short courses/forums, an exhibition, social and networking activities. It aims to provide a good coverage of technological developments in all areas of electronic packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts in the field.

Since its inauguration in 1997, EPTC has developed into a highly reputed electronics packaging conference in Asia and is well attended by experts in all aspects related to packaging technology from all over the world.

CONFERENCE TOPICS

You are invited to submit an abstract, presenting new development in the following categories:

- ❑ **Advanced Packaging:** Wafer level packaging, 3D integration, TSV (through Silicon Via), embedded passives & actives on substrates, flip chip packaging, RF-ID, 3D SiP, Packaging solutions for MEMS and MOEMS
- ❑ **Interconnection Technologies:** wire bonding technology, flip chip technology, solder alternatives (ICP, ACP, ACF, NCP), and TSV
- ❑ **Materials & Processes:** Materials and processes for traditional and advanced microelectronic systems, 3D packages, MEMS, solar, green and biomedical packaging
- ❑ **Modeling & Simulation:** Electrical modeling & signal integrity, thermal characterization & cooling solutions, mechanical modeling & structural integrity
- ❑ **Quality & Reliability:** Component, board and system level reliability assessment, interfacial adhesion, accelerated testing and models, advances in reliability test methods and failure analysis
- ❑ **Emerging Technologies:** Packaging technologies in biomedical, bioengineering, biosensors and wearable electronics
- ❑ **Printed Electronics:** Printed devices: transistors, batteries and memory, large area printed functional films: lighting, sensors and photovoltaics, solution processing of organic and inorganic materials
- ❑ **Wafer/Package Testing and Characterization:** High-speed test architectures and systems, test methodologies, probe card design

IMPORTANT DATES

Submission of abstract	15th June 2010
Notification of Acceptance	1st August 2010
Submission of manuscript	1st October 2010

ABSTRACT AND PAPER SUBMISSION

Abstracts are solicited to describe original and unpublished work. The abstract should be at least 500 words and it must clearly state the purpose, results (including data, drawings, graphs and photographs) and conclusion of the work. Key references to prior publications and how the work enhances existing knowledge should be included in the abstract as well.

Authors must designate two appropriate categories (found under CONFERENCE TOPICS) for abstract review. All submissions must be in English and should be made via the online submission system found at <http://www.eptc-ieee.net>. The required file format is Adobe Acrobat® PDF or MS Word in one single file for each submission.

The abstracts must be received by 15th June, 2010. Authors must include their affiliation, mailing address, telephone and fax numbers, and email address. Authors will be notified of paper acceptance and publication instruction by 1st August 2010. The final manuscript for publication in the conference proceedings is due by 1st October 2010. Selected papers will be published in IEEE/CPMT journals.

OUTSTANDING TECHNICAL PAPERS

The conference proceeding is an official IEEE publication. Author(s) of Best Technical Paper and Best Student Paper will receive an award at the next conference.

CALL FOR SHORT COURSES

The conference program includes short courses which will be conducted by leading experts in the field. Details will be updated in the conference website and available in subsequent mailings. Proposals for short courses can be submitted to techchair@eptc-ieee.net

CALL FOR SPONSORSHIP / EXHIBITION PARTICIPATION

A tabletop exhibition featuring suppliers of materials, equipment, components, software and service providers of the microelectronics and electronic assembly industries will be held during the conference. Potential exhibitors and sponsors may email secretariat@eptc-ieee.net for details.

Organized by



IEEE Reliability/CPMT/ED Singapore Chapter

General Chair:

Dr. Seung Wook YOON, STATS CHIPPAC LTD

Technical Chair:

Dr. Albert LU, SIMTech

Sponsored by





Third International Conference on Thermal Issues in Emerging Technologies Theory and Applications

ThETA 3 – Cairo – Egypt, December 19th – 22nd 2010

Objectives: Emerging Technologies in various domains, including Microelectronics, Nanotechnology, Smart Materials, Micro-Electro-Mechanical Systems, Biomedical engin., New Energies ..., all raise issues related to thermal effects and interactions. Their importance is continuously increasing, tending to be a dominant factor in new technologies.

The first two rounds have gathered participants from eminent academic and industrial institutions:

Papers presented by region	ThETA1	ThETA2
Asia (mainly Japan, S. Korea ...)	10	18
USA & Canada	7	17
Europe (mainly Italy, France ...)	14	17
Arab world	6	11

Papers appeared in IEEE/Xplore, a selection appeared in special issues of ASME/J Heat Transfer & J Elec. Pack.

Periodicity: Bi-annual

Language: English. French contributions are welcomed with extended English abstracts.

Topics:

- Micro and nano-scale heat transfer, microfluidics
- Modeling of multiple scale heat transfer problems
- Thermal modeling of electronic systems
- Temperature aware computer systems design
- Cooling of electronic systems and data centers
- Thermo-mechanical analysis in electronic systems
- MEMS – multi-physics problems
- New and renewable energies, energy conservation
- Fuel cells
- Solid state energy generation / cooling
- Energy – Buildings - environment
- Multiphase flow with heat transfer
- Thermal issues in biomedical engineering
- Thermal issues in micro-fabrication technology
- Thermal issues in new materials
- Computational methods in heat transfer
- New experimental methods in heat transfer

Executive committee:

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Conference papers will appear in IEEE/Xplore A
selection will appear in ASME/JHT & ASME/JEP

Submitting abstracts:

Send a ~1000 words abstract, in any of the following formats: .txt, .pdf, .doc, .sxw to: thetacnf@gmail.com

Deadlines:

Submitting abstracts	May 30 th 2010
Notification of abstract acceptance	Jun. 27 th 2010
Submitting full papers	Aug. 15 th 2010
Notification of paper acceptance	Oct. 3 rd 2010
Final camera-ready full paper	Nov. 3 rd 2010

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